



HTIF102

NPN EPITAXIAL PLANAR TRANSISTOR

Description

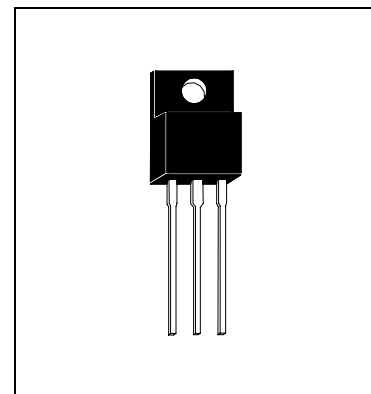
The HTIF102 is designed for use in general purpose amplifier and low-speed switching applications.

Absolute Maximum Ratings (Ta=25°C)

- Maximum Temperatures
Storage Temperature -55~+150°C
Junction Temperature +150°C Maximum
- Maximum Power Dissipation
Total Power Dissipation (Tc=25°C) 55 W
- Maximum Voltages and Currents
BVCBO Collector to Base Voltage 100 V
BVCEO Collector to Emitter Voltage 100 V
BVEBO Emitter to Base Voltage 5 V
IC Collector Current 8 A

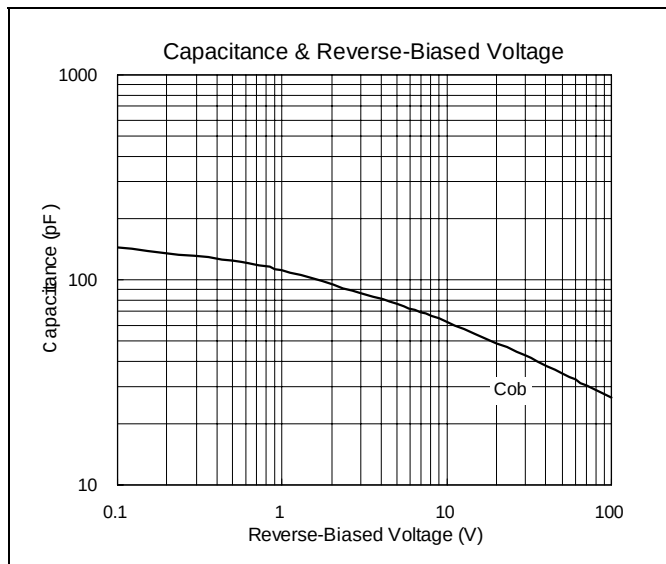
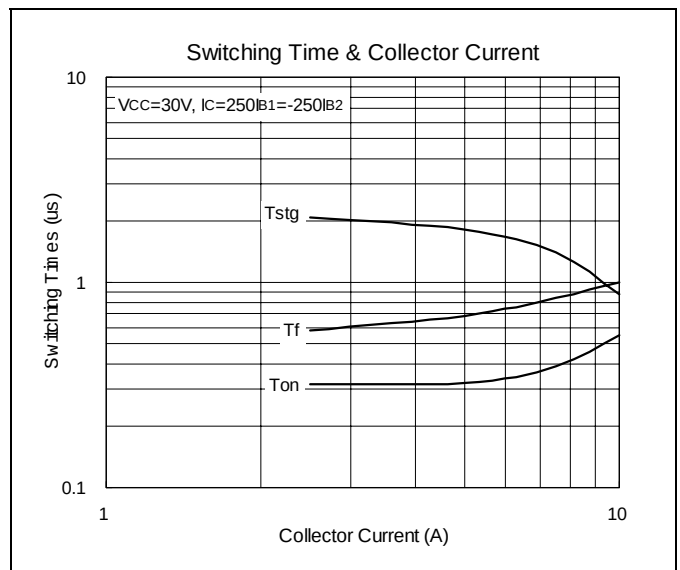
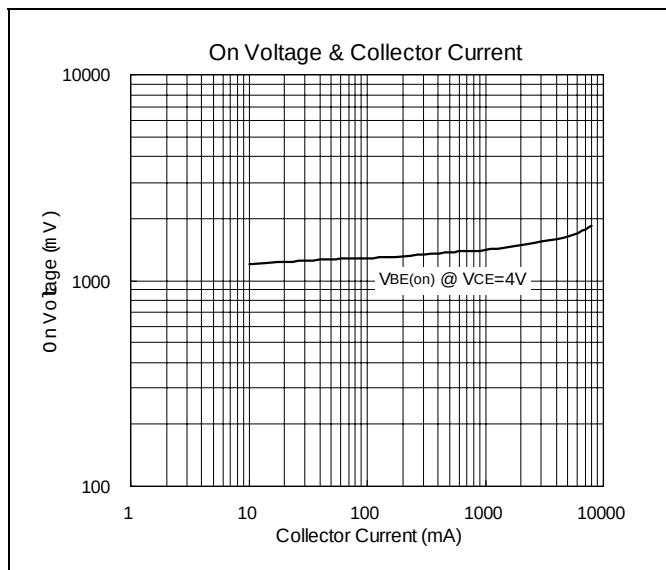
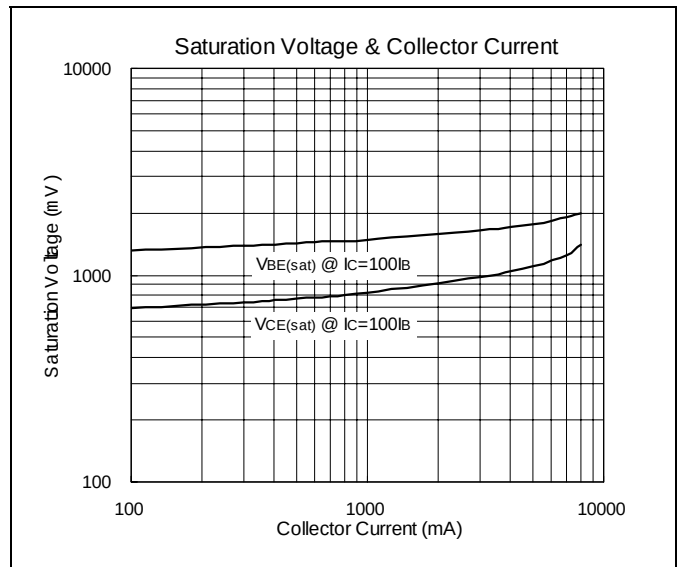
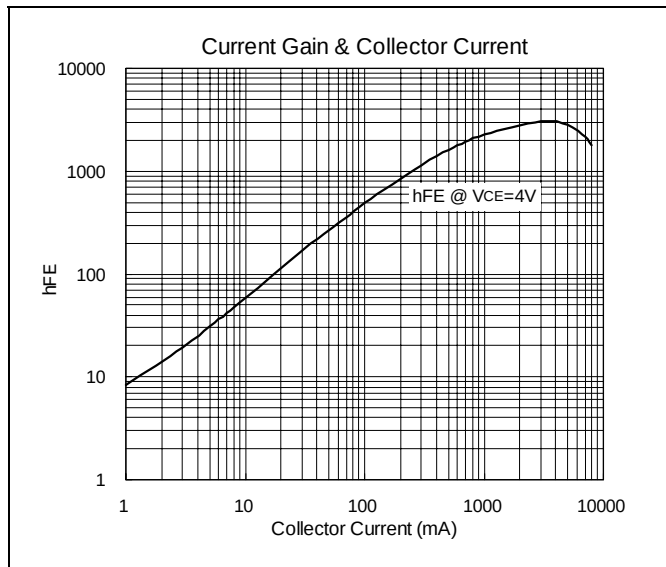
Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	100	-	-	V	IC=1mA
BVCEO	100	-	-	V	IC=30mA
ICBO	-	-	50	uA	VCB=100V
ICEO	-	-	50	uA	VCE=50V
IEBO	-	-	8	mA	VEB=5V
VCE(sat)1	-	-	2	V	IC=3A, IB=6mA
VCE(sat)2	-	-	2.5	V	IC=8A, IB=80mA
VBE(on)	-	-	2.8	V	IC=8A, VCE=4V
hFE1	1	-	20	K	IC=3A, VCE=4V
hFE2	200	-	-		IC=8A, VCE=4V
Cob	-	-	200	pF	VCB=10V



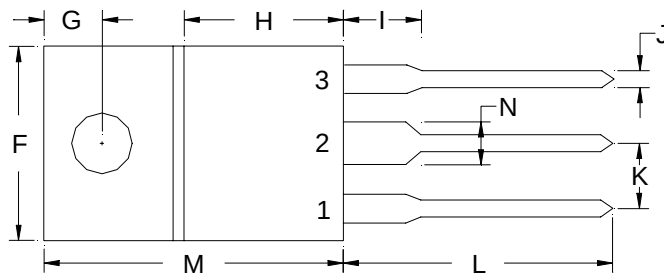
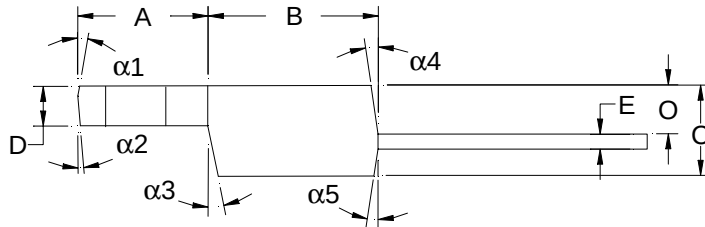


Characteristics Curve



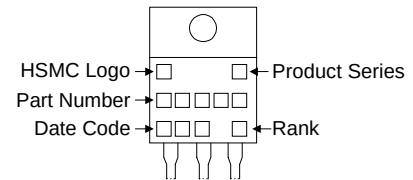


TO-220FP Dimension



3-Lead TO-220FP Plastic Package
HSMC Package Code : F

Marking :



Style : Pin 1.Base 2.Collector 3.Emitter

*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.2480	0.2520	6.30	6.40	K	-	*0.1004	-	*2.55
B	0.3386	0.3425	8.60	8.70	L	0.5118	0.5906	13.00	15.00
C	0.1673	0.1870	4.25	4.75	M	0.5886	0.5925	14.95	15.05
D	0.1043	0.1083	2.65	2.75	N	-	*0.0669	-	*1.70
E	0.0230	0.0242	0.58	0.61	O	0.1098	0.1114	2.79	2.83
F	0.3980	0.4039	10.11	10.26	1	-	-2°	-	*2°
G	0.1083	0.1122	2.75	2.85	2	-	*5°	-	*5°
H	0.3386	0.3425	8.60	8.70	3	-	*15°	-	*15°
I	-	*0.1496	-	*3.80	4	-	*5°	-	*5°
J	-	*0.0236	-	*0.60	5	-	*5°	-	*5°

Notes : 1.Dimension and tolerance based on our Spec. dated Sep. 07,1997.

2.Controlling dimension : millimeters.

3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.

4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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